

U.S.S.N. 10,811,621

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Claim Amendments

Please amend claims 1, 2, 6, 9, 12, 18, and 19 as follows:

Please cancel claims 3, 8, 10, 11, and 14-16 as follows:

Please add new claims 21-26 as follows:

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Listing of Claims

1. (currently amended) An electrolyte bath, comprising:

an electrolyte solution suitable for metal electroplating; and

a composition comprising an organic acid and a non-ionic polymer mixed with said organic acid, said non-ionic polymer selected from the group consisting of an alkoxyated alcohol, an alkoxyated amine, and an alkylphenol alkoxyate;

wherein said composition is disposed as a suspension layer within said electrolyte solution, said suspension layer of sufficient dimension to form a wetting layer on a substrate as said substrate is passed through said suspension layer.

2. (currently amended) The electrolyte bath of claim 1 wherein said organic acid is selected from the group consisting of citric acid ~~or~~ and acetic acid.

3. (canceled)

4. (previously presented) The electrolyte bath of claim 1 wherein

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said composition is present in said electrolyte solution in a concentration of about 5 % by weight.

5. (previously presented) The electrolyte bath of claim 1 wherein said non-ionic polymer has a molecular weight of less than 1,000.

6. (currently amended) The electrolyte bath of claim 5 wherein said organic acid is selected from the group consisting of citric acid or and acetic acid.

7. (previously presented) The electrolyte bath of claim 1 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

8. (canceled)

9. (currently amended) An electrolyte bath, comprising:

an electrolyte solution suitable for copper electroplating; and

a ~~second~~ composition comprising an organic acid and a non-ionic polymer mixed with said organic acid, said non-ionic

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polymer selected from the group consisting of an alkoxyated alcohol, alkoxyated amine, and an alkylphenol alkoxyate, said organic acid selected from the group consisting of citric acid and acetic acid;

wherein said composition is disposed as a suspension layer within said electrolyte solution, said suspension layer of sufficient dimension to form a wetting layer on a substrate as said substrate is passed through said suspension layer.

10. (canceled)

11. (canceled)

12. (currently amended) The electrolyte bath of claim [[11]] 9 wherein said composition is present in said electrolyte solution in a concentration of about 5% by weight.

13. (previously presented) The electrolyte bath of claim 9 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

Claims 14-16 (canceled)

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17. (previously presented) A method for electroplating a metal onto a surface in an electroplating electrolyte solution, comprising the steps of:

providing a composition mixture comprising an organic acid and a non-ionic polymer;

forming a suspension layer of said composition mixture within said electrolyte solution;

forming a wetting layer on said surface by passing said surface through said suspension layer and into said electrolyte solution; and

electroplating said metal onto said surface following forming said wetting layer.

18. (currently amended) The method of claim 17 wherein said organic acid is selected from the group consisting of citric acid ~~or~~ and acetic acid and said non-ionic polymer is selected from the group consisting of an alkoxylated alcohol, an alkoxylated amine, ~~or~~ and an alkylphenol alkoxylate.

19. (currently amended) The method of claim ~~[[17]]~~ 18 wherein

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said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

20. (original) The method of claim 17 further comprising a substrate and wherein said surface comprises a metal seed layer deposited on said substrate.

21. (new) The electrolyte bath of claim 1, wherein said non-ionic polymer is present in said suspension layer in a quantity of from about 0.5 to about 10 wt. %.

22. (new) The electrolyte bath of claim 1, wherein said organic acid is present in said suspension layer in a quantity of from about 2 to about 20 wt. %.

23. (new) The electrolyte bath of claim 9, wherein said non-ionic polymer is present in said suspension layer in a quantity of from about 0.5 to about 10 wt. %.

24. (new) The electrolyte bath of claim 9, wherein said organic acid is present in said suspension layer in a quantity of from about 2 to about 20 wt. %.

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25. (new) The method of claim 17, wherein said non-ionic polymer is present in said suspension layer in a quantity of from about 0.5 to about 10 wt. %.

26. (new) The method of claim 17, wherein said organic acid is present in said suspension layer in a quantity of from about 2 to about 20 wt. %.